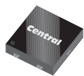
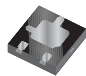
Material Composition Specification
TLM322S Case


Top View


Bottom View

Device average mass . . . . 6.0 mg
Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.167%	0.07	Si	7440-21-3	1.167%	0.07	11,667
bond wire	gold	0.5%	0.03	Au	7440-57-5	0.5%	0.03	5,000
leadframe	Cu alloy	24.5%	1.47	Cu	7440-50-8	23.167%	1.39	231,667
				Ni	7440-02-0	0.867%	0.052	8,667
				Ag	7440-22-4	0.233%	0.014	2,333
				Zn	7440-66-6	0.117%	0.007	1,167
				Si	7440-31-5	0.117%	0.007	1,167
die attach	silver epoxy	0.3%	0.018	epoxy resin	Proprietary	0.067%	0.004	667
				Ag	7440-22-4	0.233%	0.014	2,333
encapsulation*	EMC GREEN	71.066%	4.264	silica (fused)	60676-86-0	66.583%	3.995	665,833
				epoxy resin	29690-82-2	2.133%	0.128	21,333
				phenol resin	9003-35-4	2.133%	0.128	21,333
				carbon black	1333-86-4	0.217%	0.013	2,167
plating	matte tin	2.467%	0.148	Sn	7440-31-5	2.467%	0.148	24,667

*EMC GREEN molding compound is Halogen Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (11-January 2012)